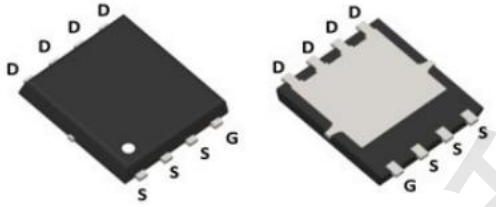
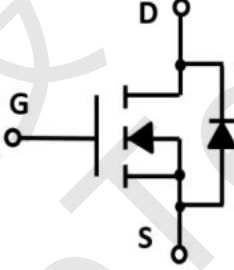




### FMB6080G N-Channel Trench Power MOSFET

#### FMB6080G Description

<b>Features</b> <ul style="list-style-type: none"> <li>• 60V,80A</li> <li>• <math>R_{DS(ON)}=5.9m\Omega</math> (Typ.) @ <math>V_{GS}=10V</math></li> <li>• Advanced Trench Technology</li> <li>• Provide Excellent <math>R_{DS(ON)}</math> and Low Gate Charge</li> </ul>	<b>Application</b> <ul style="list-style-type: none"> <li>• LCD TV</li> <li>• Notebook</li> <li>• Elevator</li> <li>• Inductive heating</li> <li>• Power tools</li> </ul>
<b>Package</b> <div style="display: flex; justify-content: space-around; align-items: center;"> <div style="text-align: center;">  <p>PDFN-8 (5*6)</p> </div> <div style="text-align: center;">  <p>Schematic diagram</p> </div> </div>	

#### FMB6080G Package Marking and Ordering Information

Product ID	PACK	Qty (pcs)
FMB6080G	PDFN-8(5*6)	4000

#### FMB6080G Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DSS}$	Drain-Source Voltage	60	V
$V_{GSS}$	Gate-Source Voltage	$\pm 25$	V
$I_D$	Continuous Drain Current	$T_c = 25^\circ\text{C}$	80
		$T_c = 100^\circ\text{C}$	36
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>	170	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>	380	mJ
$P_D$	Power Dissipation	$T_c = 25^\circ\text{C}$	33.2
$R_{\theta JC}$	Thermal Resistance, Junction to Case	3.77	$^\circ\text{C/W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$



### FMB6080G Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =48V, V <sub>GS</sub> =0V,	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±25V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	2.9	4.0	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance <small>note3</small>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	5.9	7.6	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =20A	-	19	-	S
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, f=1.0MHz	-	6208	-	pF
C <sub>oss</sub>	Output Capacitance		-	511	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	438	-	pF
R <sub>g</sub>	Gate resistance	-	-	2.2	-	Ω
<b>Switching Characteristics</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =30V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V	-	99.1	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	22.3	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	26.7	-	nC
V <sub>plateau</sub>	Gate plateau voltage		-	4.5	-	V
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V RL=1.5Ω, R <sub>GEN</sub> =3Ω	-	25.7	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	93.7	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	67.4	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	83.2	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	80	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	170	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =10A	-	-	1.2	V

- Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature  
 2. EAS condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=20V, V<sub>G</sub>=10V, R<sub>G</sub>=25Ω, L=0.5mH  
 3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%



### FMB6080G Typical Performance Characteristics

Figure 1: On-Region Characteristics

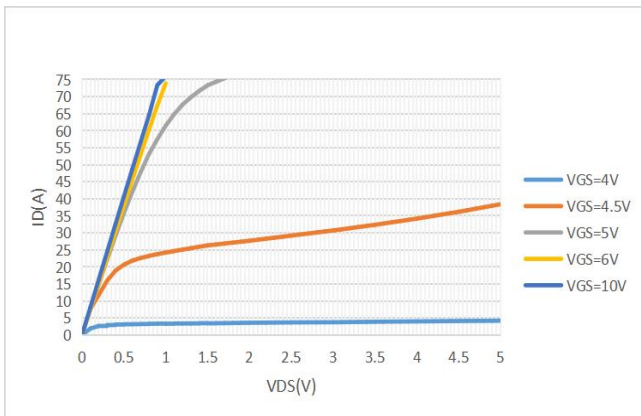


Figure 2: Transfer Characteristics

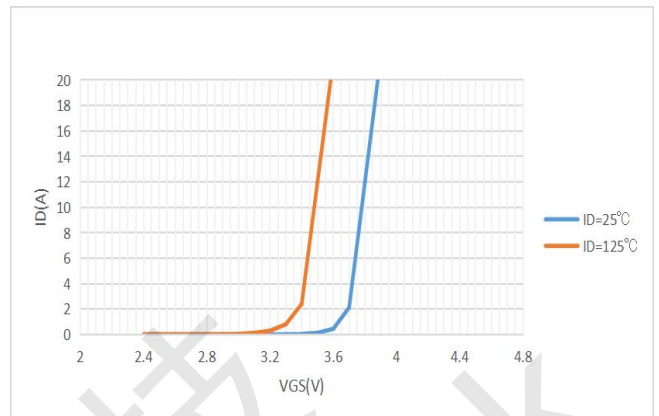


Figure 3: On-resistance vs. Drain Current and Gate Voltage

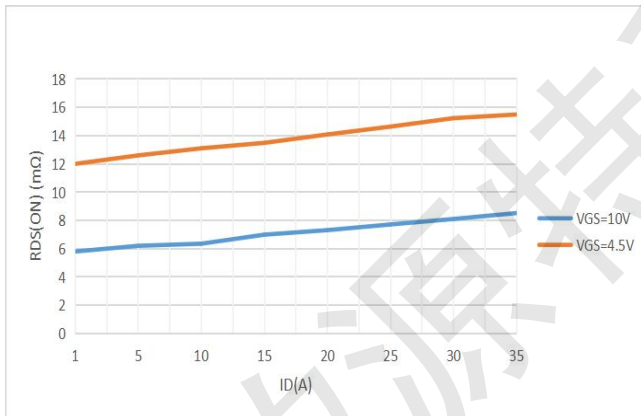


Figure 4: On-Resistance vs. Gate-Source Voltage

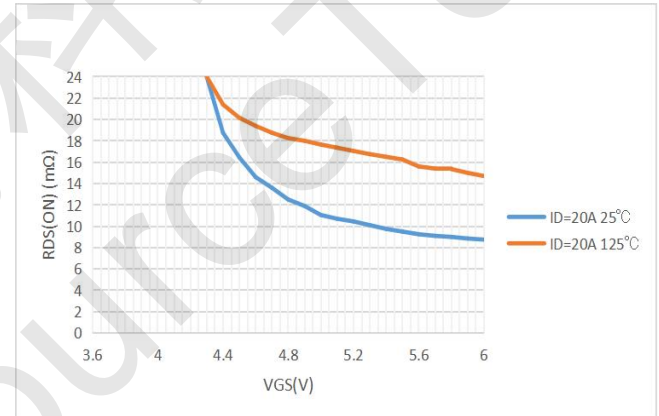


Figure 5: On-Resistance vs. Junction Temperature

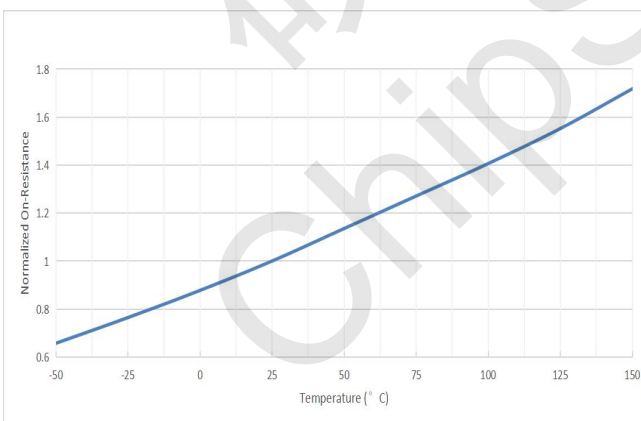
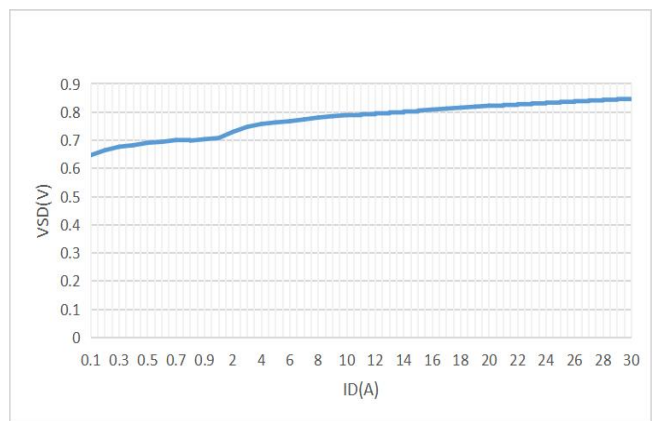


Figure 6: Body-Diode Characteristics





### FMB6080G Typical Performance Characteristics

Figure7: Capacitance Characteristics C(pF)

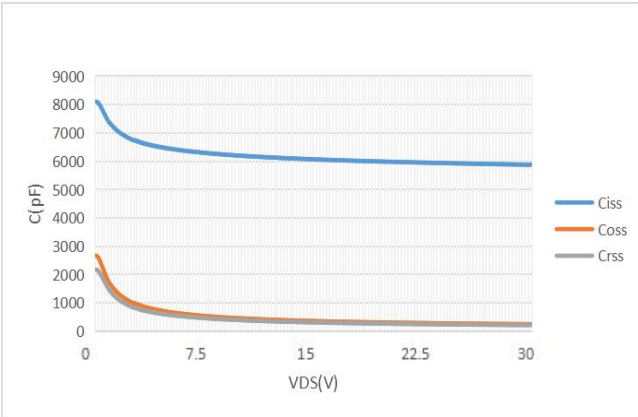


Figure 8: Current De-rating

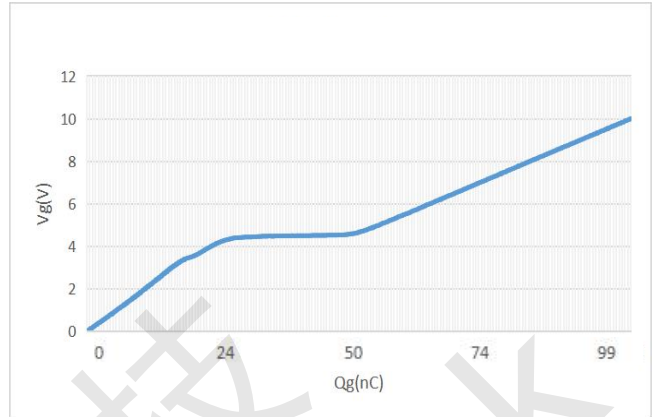


Figure9: Maximum Forward Biased Safe Operating Area

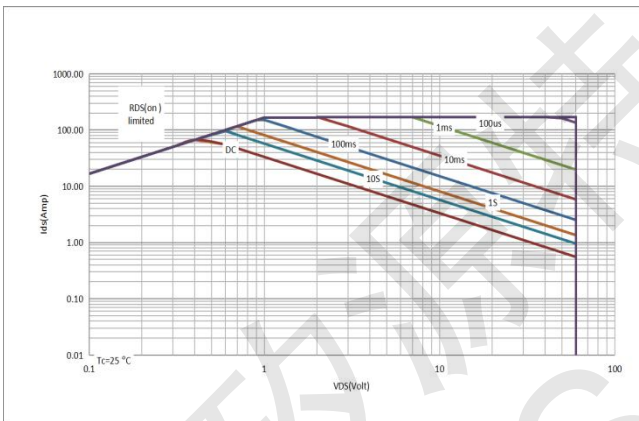
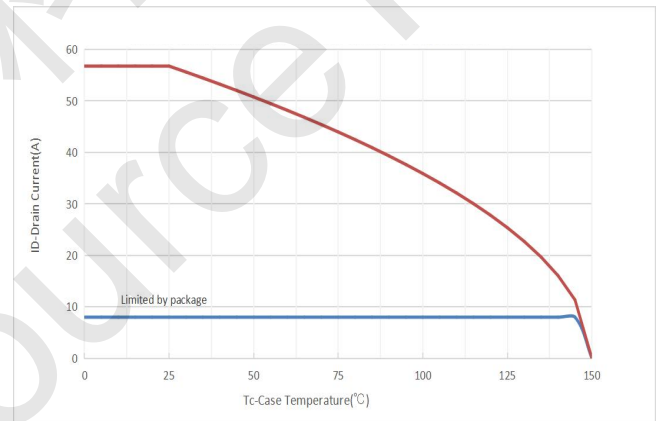


Figure 8: Current De-rating





## FMB6080G Test Circuit

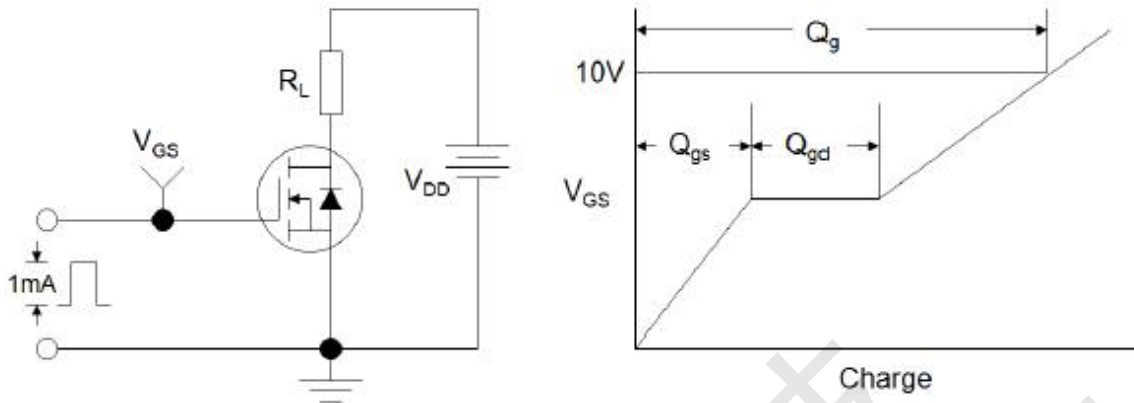


Figure1:Gate Charge Test Circuit & Waveform

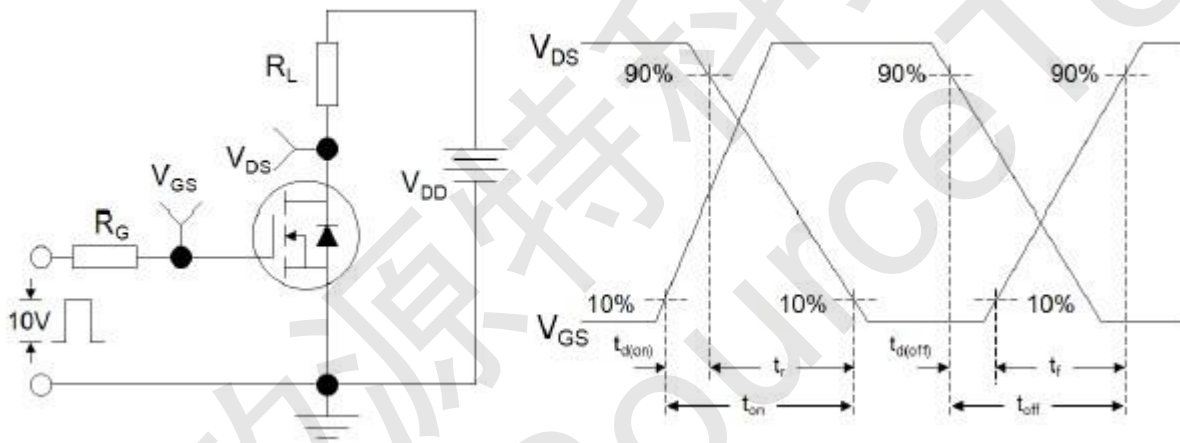


Figure 2: Resistive Switching Test Circuit & Waveforms

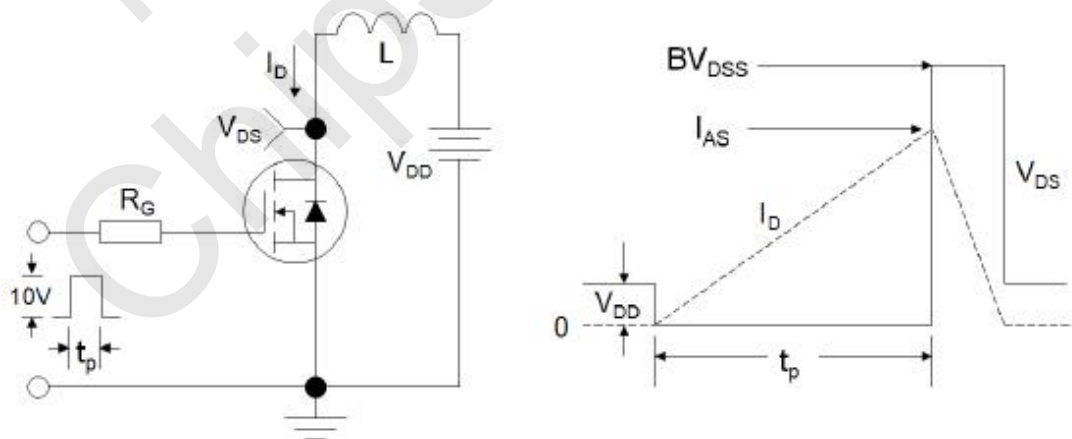


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

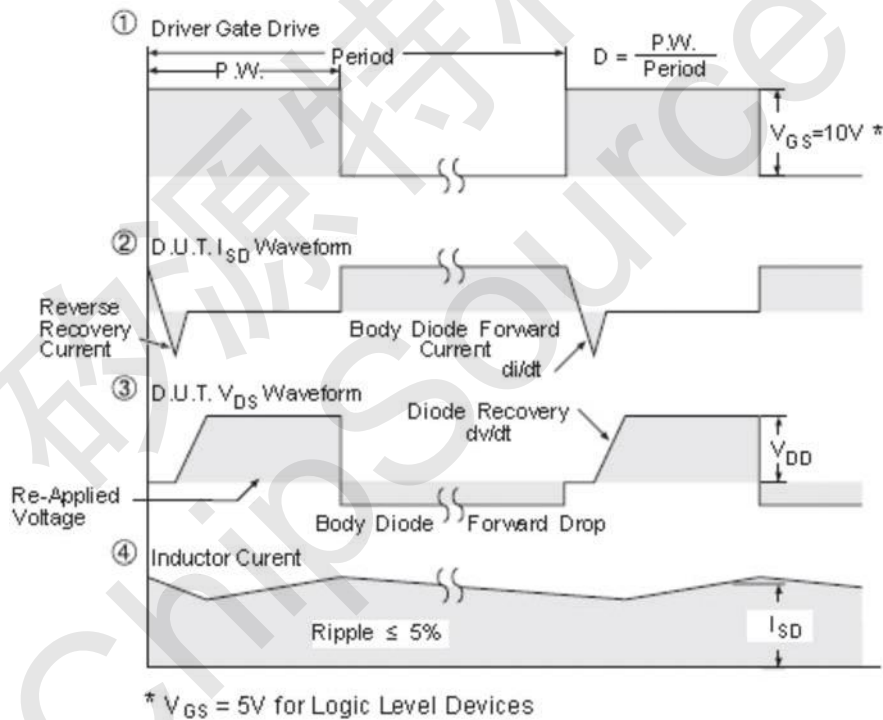
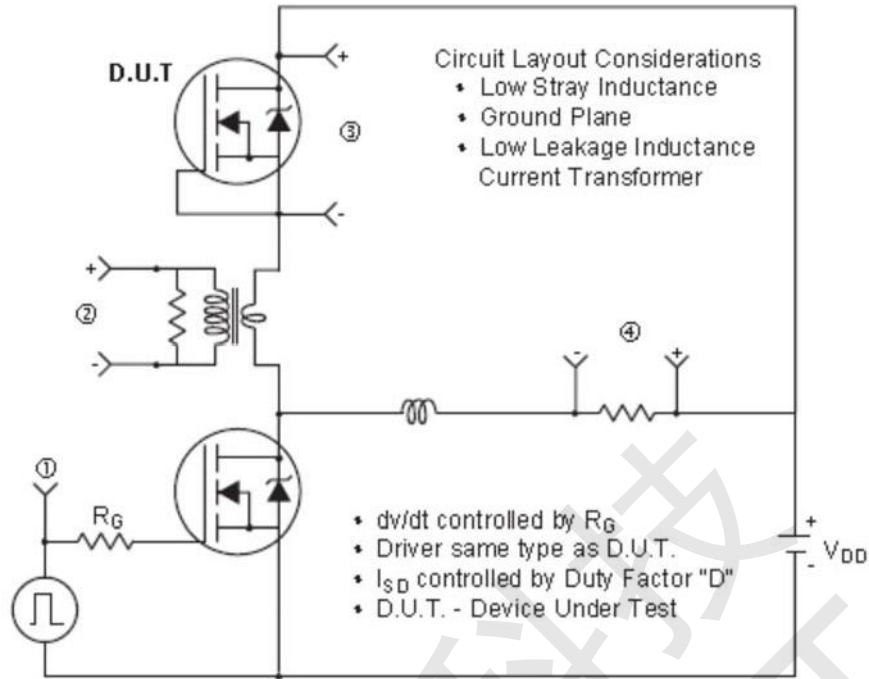
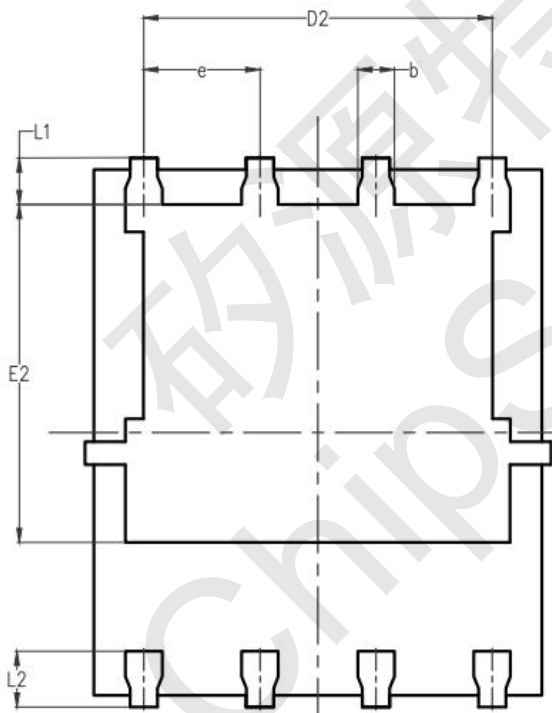
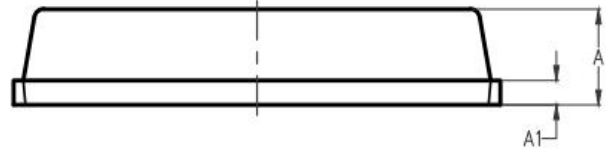
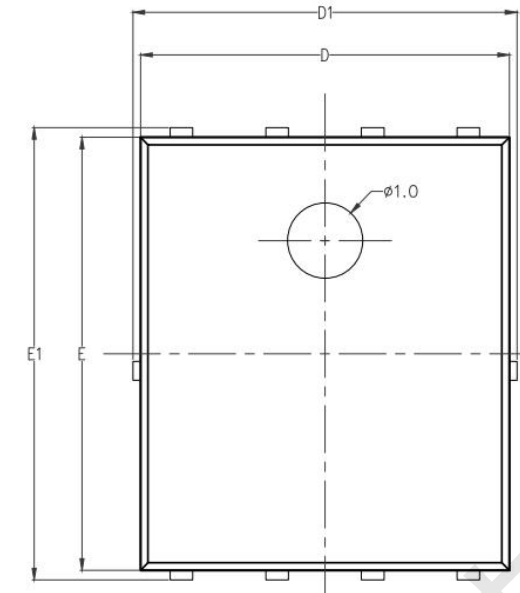


Figure 4: Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms (For N-channel)



## FMB6080G PDFN5\*6 Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.95	1.00	1.05
A1	0.254REF.		
b	0.41	0.46	0.51
D	4.85	4.90	4.95
D1	4.90	5.00	5.10
D2	3.766	3.816	3.866
E	5.696	5.746	5.796
E1	5.95	6.00	6.05
E2	3.525	3.575	3.625
e	1.22	1.27	1.32
L1	0.46	0.51	0.56
L2	0.56	0.61	0.66